

ABSTRACT

Solder paste application, inspection and correction.

5 Following or during application of solder paste on a substrate, the result thereof is inspected and any detected errors are registered. Following an evaluation as to whether correction of these errors is required and if it would be worthwhile, the errors are corrected. The correction involves removing solder paste from locations

10 where so required, and jetting of additional solder paste to locations where so required.

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